

Приборы полупроводниковой микро- и наноэлектроники

Компьютеров В.В. Вьюрков – лектор, зам. зав. кафедрой

Факультет физической и квантовой электроники (ФФКЭ МФТИ)

Физико-технологический институт Российской академии наук

План лекций

- Технология наноэлектронных приборов
- Теория наноэлектронных приборов
- •Квантовые компьютеры

Полевой транзистор – прибор с варьируемым сопротивлением



The end of Moore's 'law'?



IBM Gains Confidence in 22 nm ETSOI (IEDM Conf., Dec. 2009)



Intel Going Vertical for 22nm Transistors in 2011



Multi-gate FETs



Экспериментальный технологический маршрут изготовления МДП КНИ - нанотранзистора



Основные этапы изготовления :

- 1. Формирование STI изоляции;
- 2. Изготовление затворного стека;
- 3. Изготовление спейсеров, истока/стока;
- 5. Изготовление контактов к стоку/ истоку;
- 6. Изоляция транзистора, формирование контактных окон;
- 7. Металлизация.



Изготовление полевого транзистора



100 nm Mag = 257.38 K X EHT = 5.02 kV Date :26 Mar 2012 WD = 3.8 mm Signal A = InLens Time :14:38:13

Изготовление полевого

транзистора







Электронный литограф Raith-150



- 150x150mm stage for direct writing over 6" wafers
- Automatic airlock for sample loading
- Schottky thermal field-emission filament
- 200V-30kV beam acceleration
- 2pA-10nA beam current
- 2nm beam resolution at 20kV
- Laser interferometer for stage positioning with ~30nm precision

Аналитический автоэмиссионный растровый электронный микроскоп для исследования наноструктур ULTRA ZEISS



Установка атомно-слоевого осаждения FlexAl (Oxford Instruments Plasma Technology)



Substrates	Up to 200mm wafers handling and pieces on carrier plate
Precursosrs	Bubbled liquid and solid precursors
Max precursor source temperature	200ºC (oven and jacket)
Additional precursors	Water + ozone
Mfc controlled gas lines with rapid delivery system	1) thermal gas precursors (e.g. NH_3 , O_2) 2) plasma gases (e.g. O_2 , N_2 , H_2)
In situ diagnostic features	Ellipsometry, OES
Swagelok 10ms rapid pulsing ALD valves	Yes
Removable inner chamber	Yes
Wafer stage temperature range	550°C

Установки фотолитографии (Zuss) и нанесения резиста (Sawatec)





Установка плазмохимического травления Plasma Lab 100 Dual (Oxford Instruments Plasma Technology)

	ICP Etch(380)
Загрузка	шлюз
Подложки	до 200 мм
Диапазон температур	от -140°С до +400°С
Возбуждение плазмы	ВЧ
Линий газоподачи с РРГ	до 12 на каждую камеру
Плазменная очистка камеры	есть
Вакуумная система	ТМН
Система управления	PC2000
Рабочие газы	HCl, C4H8, CF4, SF6, O2



Установка быстрого фотонного отжига Annealsys AS-100

- Pyrometer and thermocouple control
- Fast digital PID temperature controller
- Temperature range: RT to 1200°C
- Ramp rate up to 200°C/s
- Cooling rate up to 100°C/s
- RTA (Rapid Thermal Annealing)
- RTO (Rapid thermal oxidation)
- Diffusion, contact annealing
- Nitridation





Теория наноэлектронных приборов

- Требования современной электроники: Low-power и High-performance
 - Альтернативные механизмы переноса тока: туннелирование
 - Альтернативные материалы: графен и его модификации
 - Масштабирование традиционных полевых транзисторов;



Эволюция моделей

электронного транспорта

Charged waves: Schrödinger equation

> **Charged particles**: Boltzmann kinetic equation



Charged fluid: Hydrodynamic equations

Квантовые эффекты в

полевых нанотранзисторах

Поперечное квантование;

статистика.

 Туннелирование и интерференция электронных волн;
 Квантовая GATE DRAIN Si CHANNEL SOURCE GATE INSULATOR WAFER



Silicon conduction band

structure

 Effective mass and transversal quantization energy



$$m_t = 0.19m_0, m_l = 0.98m_0$$

$$\varepsilon_0 = \frac{\mathbb{Z}^2}{2m} \left[\frac{\pi}{d_{Si}} \right]^2$$

Landauer-Büttiker formalism



Transversal quantization \Rightarrow

Landauer-Buttiker formalism

(wave-guide modes) in a channel
$$\Rightarrow I(V_D) = \frac{2e}{h} \sum_{v} \sum_{i} \sum_{j} \int dET_{ij}(E) [f_S(E) - f_D(E)]$$

Everlasting controversy in kinetic simulation

- Distribution function (equilibrium) is known only in contacts
- Strong scattering in contacts

Heavy doping – low doping junction

at S/D contact



Few of incident particles surmount the barrier => Equilibrium distribution for particles coming in the channel

Analytical solution obtained for modified (BGK) collision integral in T-approximation

High self-consistent barrier at S/D contacts

Main strategy of simulation

Self-consistent solution of

Schrödinger equation
+
Maxwell equation
(Poisson equation)

Solution of 3D Schrödinger

equation $-\frac{\boxtimes^2}{2m}\Delta\Psi(x,y,z) + V(x,y,z)\Psi(x,y,z) = \varepsilon\Psi(x,y,z)$ V(x,y,z) is a potential.

The direct solution of the stationary 3D Schrödinger equation via a finite difference scheme comes across a well known instability caused by evanescent modes.

In fact, the exponential growth of upper modes makes a computation impossible.

D.K.Ferry et al. (2005) (США, Arizona State University): results of simulation



Solution of Schrödinger equation: transverse mode representation + high-precision arithmetic

•
$$\Psi(x, y, z) = \sum_{i=1}^{N} a_i(x) \psi_i(y, z)$$

where $\psi i(y,z)$ is the i-th transverse mode wave function, N is a number of involved modes.

The space evolution of coefficients $a_i(x)$ is governed by matrix elements

$$M_{ij}(x) = \langle \psi_i(y,z) | V(x,y,z) | \psi_j(y,z) \rangle$$

The off-diagonal elements M_{ii} manage the mode conversion.

The diagonal elements M_{ii} manage the quantum reflection, interference and tunneling of the i-th mode.

Calculated transmission coefficient T(E) vs. electron energy E

(4 random impurities in a channel)



[100] and [010] valleys

[001] valleys

Transistor parameters are 10nm channel length and width, 5nm body thickness, 10²0 cm⁻³ source/drain contact doping, 5nm contact length.

Gate voltage characteristics



Sub-threshold swing is 71 mV per decade of current.

Impurities in channel:



0

Impurities in channel:



0

Corrugated channel:



Corrugated channel: _____



Dispersion of characteristics

5-15% in calculated I-V curves

< 10% is an everlasting condition for large integrated circuits</p>

More severe demands to technology may arise.

• Требования к современной электронике
Требования к современной электронике: 1) high performance

- RC задержка инвертора
- delay time = Rin * Cout
- Необходима высокая проводимость канала транзисторов и малый размер транзистора

Предельная частота:пролётное время

$$f_{\max} = \frac{v}{L_{ch}}$$

- Необходима малая длина канала (Intel – 22nm)
- и/или высокая подвижность (новые материалы)

Требования к современной электронике: 2) low power

 Потребляемая активная мощность

$$P_a = \frac{CV_{DD}^2}{2}f$$

 Необходимо малое напряжение питания и быстрое переключение между состояниями • Пассивная мощность

$$P_p = I_{OFF} V_{DD}$$

- Необходим малый ток в закрытом состоянии
 - Большое отношение

$$I_{ON} / I_{OFF}$$

Снижение энергопотребления



Предельная крутизна переключения: 60 мВ/дек для термоэмиссионого механизма переноса тока Как сделать круче?

Туннельные транзисторы позволяют достичь подпороговой крутизны выше (60мВ/дек)-1 при комнатной температуре

Tunnel FET vs. thermionic FET



$$I \propto \exp\left[-\frac{eV_B}{kT}\right]$$
$$\frac{d\ln I}{dV_G} \le \frac{e}{kT} = (60 \text{ mV/dec})^{-1}$$

TT 7

Γ.

Limits the drive voltage V_{DD}>240 mV to achieve 4 decade switching

$$I \propto \left[E_{v} - E_{c} \left(V_{G} \right) \right]^{\alpha} \exp \left[-\frac{F_{cr}}{F \left(V_{G} \right)} \right]$$
$$\frac{d \ln I}{d V_{G}} \bigg|_{E_{c} \to E_{v}} \to \infty$$

Low voltage switching possible – low power operation

Tunnel transisors

Shottky-barrier FET

- Gate-controlled reverse-biased Shottky junction
- Intraband metal-semiconductor tunneling



Interband tunnel FET

Valence

- Gate-controlled reverse-biased Esaki junction
- Valence-to-conduction band tunneling
 <u>Conduction</u>

OFF

ON

Shottky-barier TFETs:

ultimate subthreshold slope

$$I = I_{tun} + I_{therm}$$
$$I_{therm} \propto \exp\left\{-\frac{\Phi_b}{kT}\right\}$$
$$I_{tun} \propto \exp\left\{-\frac{4}{3}\frac{\sqrt{2m\Phi_b^3}}{e^{\mathbb{N}}F(V_G)}\right\}$$

The subthreshold slope of tunnel component is large only when tunnel component is small and masked by thermionic current □ The (60 mV/dec)-1 limit persists for SB FET despite the presence of tunneling



Schematic view of current components in SB FET vs gate voltage illustrating the impossibility to achieve subthermal steepness

D. Svintsov et.al. Semiconductors 47, p. 279 (2013) W. G Vandenberghe. et al. Appl. Phys. Lett. 102, 013510 (2013)

TFETs subthreshold: state of the



FIGURE 3. Published [26], [29], [31], [32], [37], [39], [47] and extracted [27], [28], [30], [33], [35], [41] TFET sub-threshold swing versus drain current per unit width for *n*-channel (circle with solid line) and *p*-channel (diamond symbol with dashed line) TFETs that show SS near or below 60 mV/decade at room temperature. With the exception of the CNT TFETs [48], [49] this is a comprehensive plot showing 12 TFETs with reported SS below 60 mV/decade.

H. Lu ans A.C. Seabaugh IEEE Journal of the Electron Devices Society 2 p. 44-49 (2014)



Limits of the subthreshold

slope: band tails



E.O. Kane 1963 Phys. Rev 131 p. 79

Comparison of TFET modeling with perfectly flat bands (dashed) and taking into account the band tails (solid)

Multigate TFET with electrically induced p-n junction









Simulated characteristics of



- •Gate dielectric 2 nm, κ=25 (e.g. HfO₂);
- •Distance between gates ("doping" and "control" gates) is 2 nm;
- •10 nm SOI thickness;

•Better subthreshold due to tunneling in undoped region (no band tails);

•Higher current due to abrupt screening of potential below the "doping" gate.

Simulated I(V_G)-curve for multigate FET with electrically induced junctions (MG TFET, solid) and common FETs with doped source and drain Graphene FETs



Graphene structures





Deposited or **epitaxial** (on **SiC or hBN**) graphene: mobility 5000-10000 cm²/V s due to interface defects and bulk phonons Suspended graphene or twisted graphene stack: mobility 100000-200000 cm^2/V s

no interface defects and bulk phonons

олектропные своиства

графена







Модель транспорта электронов в графене

Высокая частота межэлектронных столкновений позволяет описывать транспорт в гидродинамической модели

$$\frac{\partial \left(\boldsymbol{\rho}_{e} u_{e}\right)}{\partial t} + \frac{\partial}{\partial x} \left(\frac{\boldsymbol{\varepsilon}_{e}}{2} \left[1 + 2\left(\frac{u_{e}}{v_{F}}\right)^{2}\right]\right) - en_{e} \frac{\partial \boldsymbol{\varphi}}{\partial x_{i}} = -\boldsymbol{\beta}_{e-i} u_{e} - \boldsymbol{\beta}_{eh} \left(u_{e} - u_{h}\right),$$
$$\frac{\partial \left(\boldsymbol{\rho}_{h} u_{h}\right)}{\partial t} + \frac{\partial}{\partial x} \left(\frac{\boldsymbol{\varepsilon}_{h}}{2} \left[1 + 2\left(\frac{u_{h}}{v_{F}}\right)^{2}\right]\right) + en_{h} \frac{\partial \boldsymbol{\varphi}}{\partial x_{i}} = -\boldsymbol{\beta}_{h-i} u_{h} - \boldsymbol{\beta}_{eh} \left(u_{h} - u_{e}\right).$$

 n_e, n_h – electron and hole concentrations ρ_e, ρ_h – electron and hole mass densities $\rho \neq nm_0$ u_e, u_h – drift velocities β_{e-i}, β_{h-i} – friction coefficients $n = \frac{n_0}{\left[1 - (u/v_F)^2\right]^{3/2}}, \rho = \frac{\rho_0}{\left[1 - (u/v_F)^2\right]^{5/2}}$

D. Svintsov, V. Vyurkov, S. Yurchenko, V. Ryzhii, T. Otsuji *"Hydrodynamic model for electron-hole plasma in graphene"*, Journal of Applied Physics, Vol. 111, p. 083715 (2012) D. Svintsov, V. Vyurkov, V. Ryzhii, T. Otsuji *"Hydrodynamic electron transport and nonlinear*

waves in graphene", Physical Review B, Vol. 88, p. 245444 (2013)

Моделирование характеристик

полевых транзисторов





Possible applications: Logic

circuits?

- Graphene
 - => **good** Ohmic source and drain contact
- Gap=o
 - => **big** OFF-state current
- Bilayers, nanoribons or graphane
 => bad Ohmic source and
 drain contact
 Gap≠o
 - => **low** OFF-state current

Graphene vertical tunnel FETs

eV_G Gate

Layout of vertical graphene tunnel FET. Tunneling occurs between two graphene layers separated by 3-10 monolayers of boron nitride Band diagram of graphene lateral TFET. The gate voltage controls the tunnel density of states, but not the barrier height

L. Britnell et al ,Science vol. **335 p. 947 (**2012**)** L. Britnell et. al., Nature Communications vol. **4** art. no. 1794 (2013)

Graphene vertical tunnel FETs

~10MHz expected due to small tunneling

probability

Measured tunnel conductivity of vertical graphene TFET vs. gate voltage

- L. Britnell et. al., Science **335** p. 947 (2012)
- T. Georgiou et. al. Nature Nanotechnology 8 p. 100 (2013)
- A. Mishchenko et. al. Nature Nanotechnology 9 p. 808 (2014)

Латеральный туннельный транзистор на основе графена

Рассчитанные характеристики, демонстрирующие насыщение тока и высокое (>10⁴) отношение токов открытого и закрытого состояний

D. Svintsov *et. al.*, Semiconductors vol. 47, p. 279-284 (2013)D. Svintsov *et. al.*, J. Phys. D: Appl. Phys. Special issue "Graphene devices" (2014)

Транзисторы на основе двухслойного графена

on Graphene Bilayer Field-Effect Transistor Characteristics", Japanese Journal of Applied Physics, Vol. 50, Iss. 7, p. 070112 (2011)

Graphene bilayer

•Gap opening up to ~o.4 eV by transverse electric field;

•Symmetric "Mexican-hat" band dispersion

Conduction and valence band electron dispersions in graphene under applied transverse electric field

Graphene bilayer

Conduction and valence band electron dispersions in graphene under applied transverse electric field

Density of states in gapped graphene bilayer demonstrating a van Hove singularity

Exploiting the van Hove

singularity in tunneling

source and drain regions (B) Band diagram of graphene bilayer TFET for the optimal biasing conditions: $V_B > 0$, $U_S < 0$, $U_D > 0$. At zero top gate bias, $V_G = 0$, the TFET is switched on, while at $V_G < 0$ it is switched off.

Schematic dependence of direct interband tunneling current on the band overlap in parabolic band semiconductors of different dimensionality (3D, 2D, 1D) and graphene bilayer.

Graphene bilayer TFET

characteristics

Calculated room-temperature gate transfer (left) and current-voltage (right) characteristics of graphene bilayer TFET at fixed bias voltages at auxiliary gates: $V_B = 3.3 \text{ V}$, $U_S = -0.6 \text{ V}$, $U_D = 0.25 \text{ V}$. Top gate dielectric is 2 nm ZrO₂, $\kappa = 25$, back gate dielectric is 10 nm SiO2, spacing between the source doping and control gates $d_g = 5$ nm, spacing between drain doping and control gates is 10 nm. The regions highlighted in yellow correspond to the drive voltage swing of 150 mV, in which sufficient ON/OFF ratio and high ON-state current are achieved. Inset: gate transfer characteristic in the log scale.

Proposed FET positioning

Observation of interband

tunneling in GBL

arXiv:1807.04703

QUANTUM COMPUTERS

Soviet mathematician **Yu. Manin** (1980) and

R. Feynman (1982) proposed to use a quantum system (quantum computer) for simulation of quantum systems.

- Shor's algorithm (1994): for integer factorization (to undermine the modern secret communication):
- N is a number of digits
- Classical factoring algorithm ~ $2^{\sqrt{N}}$
- Shor's quantum factoring algorithm ~ N^3
- Grover's algorithm (1996): search in unsorted data base of N elements
- quantum ~ , classical ~ N \sqrt{N}

BitDiscrete |0> or |1>

Qubit

Analog |0> and |1> Qubit superpositional state

 $|\psi\rangle = \alpha |0\rangle + \beta |1\rangle$

 $|\alpha|^{2} + |\beta|^{2} = 1$

Classical register vs. Quantum register

Bits Classical register |1>|0>|1>|1>|0>... N bits of information **Qubits** Quantum register

Entangled states 2^N -dimensional Hilbert space:

huge information capacity

> number200@toms in Universe

Sequential computation

Quantum parallelism of computation Great acceleration of several algorithms!

Entangled states in quantum computer: quantum parallelism

Realism and locality in quantum mechanics

EPR pair (EPR paradox => non-locality)

$$\psi = \frac{1}{\sqrt{2}} (| \leftrightarrow > | \otimes > + | \otimes > | \leftrightarrow >)$$

- EPR pair of photons is produced in non-linear crystal via down-conversion.
- One photon is in Alice disposal, the next one is in Bob's disposal.
- Wave function of Bob's photon is collapsed after Alice's measurement. Is information instantly transmitted form Alice to Bob and the relativity principle broken? No.
- The name "Eve" originates from the word "eavesdropping" подслушивание.

Bomb paradox (Elitzur и Vaidman)

=> no realism



No cloning theorem

Proof

The **linearity** of time evolution operator $U(\Delta t)$ implies

$$\begin{aligned} U(\Delta t)|\psi &= U(\Delta t)(a|0\rangle_A + b|1\rangle_A)|e\rangle_B \\ &= a|0\rangle_A|0\rangle_B + b|1\rangle_A|1\rangle_B \\ &\neq a^2|0\rangle_A|0\rangle_B + ab|0\rangle_A|1\rangle_B + ba|1\rangle_A|0\rangle_B + b^2|1\rangle_A|1\rangle_B \end{aligned}$$

Consequences:

'--' quantum computing – error correction much complicated

'++' quantum communication – secrecy is possible

Quantum communication: Alice – Bob – Eve (eavesdropping)

I. EPR pairs Alice ----- Bob ↑ EPR pair ↑

II. Single photons Alice -- ----- Bob

Realizations

of quantum computers

- Dopant atoms in silicon
- Quantum dots
- Ions in traps
- Cold atoms in optic traps
- NV-centers in diamond
- Superconducting structures: charge, phase and transmon
- 2D electron gas with Quantum Hall Effect
- 2D electron gas on Helium,
- and so on

Classical vs. Quantum

Bits Discrete |0> or |1>

Qubits Analog Qubit superpositional state |0> and |1> $|\psi \rangle = \alpha |0\rangle + \beta |1|\rangle$

Accuracy 10-4

Noise (decoherence) and technological variability!!!

Error correction???

Classical vs. quantum

Прототип 1 - квантовый компьютер на ядерных спинах атомов фосфора в моноизотопном кремнии (Кейн, 1998)

Главная технологическая операция – помещение одиночных примесных атомов фосфора в узлы кристаллической решетки моноизотопного кремния в определенных местах структуры – до сих пор не разработана.





Предыстория

- Квантовый компьютер на основе двойных квантовых точках
- *Fedichkin*, M. *Yanchenko*, K.A. *Valiev*, Nanotechnology 11, 387 (2000) 141, 146 39.
- Квантовый компьютер без перемещения заряда (борьба с декогерентизацией)
- V. Vyurkov, S. Filippov, L. Gorelik. Quantum computing based on space states without charge transfer. Physics Letters A 374, 3285-3291 (2010)
- Измерение состояния квантового регистра в канале транзистора в режиме кулоновской блокады тока
- M. Rudenko, V. Vyurkov, S. Filippov, A. Orlikovsky. Quantum register in a field-effect transistor channel. Int. Conf. "Micro- and nanoelectronics – 2014", Moscow, Russia, October 6-10, 2014, Book of Abstracts, p. q1-05

From quantum transistor to quantum computer

- Quantum confinement;
 Tunneling and interference of electron waves;
- Quantum statistics.





Quantum computer in transistor channel





1а. Технический облик -

лабораторный





Микросхема регистра с контактами

Измерительная установка

16. Технический облик коммерческий



Интегральная схема регистра с управляющей и измерительной системой

Field-defined quantum dots





Symmetric state in DQD



Asymmetric state in DQD

Basic states in a DQD Electron wave-function in a DQD



Basic states of two DQDs (without charge transfer !)



Potential in two DQDs

Wave-function of two electrons in two DQDs

Basic states of a qubit

Spin-polarized electrons:

$$\left|0\right\rangle = \frac{1}{\sqrt{2}}\left(\left|+_{1}-_{2}\right\rangle - \left|+_{2}-_{1}\right\rangle\right)$$

 $\left|1\right\rangle = \frac{1}{\sqrt{2}}\left(\left|-\right|_{1}+\right|_{2}\left|-\right|_{2}+\right|_{1}\right)$

Qubit states $|0\rangle = \frac{1}{\sqrt{2}}(|+_1-_2\rangle - |+_2-_1\rangle)$



Qubit states $|1\rangle = \frac{1}{\sqrt{2}}(|-1+2\rangle - |-2+1\rangle)$





Realization of SWAP-gate



Realization of sqrt-SWAP



 $\sqrt{SWAP} = \hat{E} \cdot \sqrt{NOT_1} \sqrt{NOT_2} \cdot \hat{E}$ $=\frac{1}{2i}\begin{pmatrix}2i & 0 & 0 & 0 & 0 & 0\\0 & 1 & i & i & -1 & 0\\0 & i & 1 & -1 & i & 0\\0 & i & -1 & 1 & i & 0\\0 & -1 & i & i & 1 & 0\end{pmatrix}$

Realization of CNOT-gate

As far as matrices 4×4 are concerned, a controlled phase shift gate is given by the formula [2]

$$(\hat{Z}_1(\pi/2) \otimes \hat{Z}_2(-\pi/2)) \cdot \sqrt{SWAP} (\hat{Z}_1(\pi) \otimes \hat{1}_2) \cdot \sqrt{SWAP},$$
 (23)

where \hat{Z} is the phase shift gate. In a similar way, direct calculation shows that in our case

$$\hat{\Pi} = \left[\left(\hat{Z}_1(\pi/2) \otimes \hat{Z}_2(-\pi/2) \right) \cdot \sqrt{SWAP} \right]^2 \\ \times \left(\hat{Z}_1(\pi) \otimes \hat{1}_2 \right) \cdot \sqrt{SWAP}.$$
(24)

Eventually, the CNOT operation looks like

$$CNOT = (\hat{1}_1 \otimes \hat{H}_2) \cdot \hat{\Pi} \cdot (\hat{1}_1 \otimes \hat{H}_2), \tag{25}$$

where \hat{H} is Hadamard's transformation:

$$\hat{1}_{1} \otimes \hat{H}_{2} = \frac{1}{\sqrt{2}} \begin{pmatrix} 1 & 0 & 1 & 0 & 0 & 0 \\ 0 & \sqrt{2} & 0 & 0 & 0 & 0 \\ 1 & 0 & -1 & 0 & 0 & 0 \\ 0 & 0 & 0 & 1 & 0 & 1 \\ 0 & 0 & 0 & 0 & \sqrt{2} & 0 \\ 0 & 0 & 0 & 1 & 0 & -1 \end{pmatrix}.$$
(26)

Coulomb blockade of current

for measurement



Dot occupied => potential barrier

Dot vacant => potential well

Rough condition of Coulomb blockade: dot size D > Bohr radius

Calculated transmission coefficients



For fairly smooth potential profile the transmission through the well tends to 1

whereas the transmission through the barrier tends to 0

Альтернативные проекты QC во ФТИАН

Квантовый регистр на основе двойных квантовых точек в оптическом резонаторе



Квантовые компьютеры на NV-центрах в алмазе

Искусственные алмазы:

теплопроводность	к > 2000 Вт/м ·К	
скорость звука	с = 17300 м/с	
плотность	ρ = 3515 кг/м ³	
модуль Юнга	Е ~ 1000 ГПа	





<u>Спиновый кубит на</u> электронных уровнях <u>NV-центра</u>



Light at the end of the tunnel

Collaboration

- Наноэлектронные технологии
- 🗧 АО Микрон и НИИМЭ
- ИФП СО РАН
- 🗧 Фраунгоферовский институт (Германия)
- Графен
- Лаборатория двумерных систем МФТИ (Д. Свинцов)
- Университет Тохоку (Япония)
- ИПТМ РАН
- ТГц
- МГУ им. М.В. Ломоносова
- ИСВЧПЭ РАН
- Квантовые компьютеры
- Лаборатория квантовой информатики МФТИ (С. Филиппов)
- МГУ им. М.В. Ломоносова
- ИФП СО РАН











Квантовые эффекты в полевых нанотранзисторах



- •Уравнение Шредингера:
- •Уравнение Пуассона:
- •Формула Ландауэра:

$$-\frac{\mathbb{A}^2}{2m}\Delta\Psi(x, y, z) + V(x, y, z)\Psi(x, y, z) = \varepsilon\Psi(x, y, z)$$
$$\Delta\varphi = -\frac{4\pi}{\varepsilon}en$$
$$I = \frac{2e}{h}\sum_{i=0}^{\infty}\int dET_i(E) [f_s(E) - f_d(E)]$$
Теория наноэлектронных приборов

- Цели современной наноэлектроники: Low-power и High-performance
 - Альтернативные механизмы переноса тока: туннелирование
 - Альтернативные материалы: графен и его модификации (в сотрудничестве с университетом Тохоку, Япония)
 - Масштабирование традиционных полевых транзисторов.

Транзисторы на основе графена: новые вопросы



 Объяснение отрицательной дифференциальной проводимости;
 Амбиполярные эффекты в полевых транзисторах – одновременное наличие электронов и дырок;

Создание инжекционных лазеров на основе графена.

V. Ryzhii, I. Semenikhin, M. Ryzhii, D. Svintsov, V. Vyurkov, A. Satou, and T. Otsuji "Double injection in graphene p-i-n structures", Journal of Applied Physics, Vol. 113, p. 244505 (2013)

Basic states in a DQD Electron wave-function in a DQD





measurement



Терагерцовые лазеры на основе графена





Создание квантовой теории оптического поглощения в графене с неравновесными носителями; Расчет рекомбинационных процессов, обусловленных взаимодействием квазичастиц.

Электронные свойства

графена



- Бесщелевой полупроводник;
 Линейный закон
 - дисперсии

$$\hat{H} = \mathbf{v}_F \begin{pmatrix} 0 & \hat{p}_x - i\hat{p}_y \\ \hat{p}_x + i\hat{p}_y & 0 \end{pmatrix}$$

$$\boldsymbol{\varepsilon}(p) = \pm p \, \mathbf{v}_F$$

Отсутствие обратного
рассеяния

$$\langle \mathbf{p} | V(\mathbf{r} - \mathbf{r'}) | \mathbf{p'} \rangle = \frac{V_q}{2} (1 + \cos \theta_{\mathbf{pp'}})$$